

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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#### SURFACE MOUNT SWITCHING DIODE ARRAY

#### **Features**

- Fast Switching Speed
- Low Capacitance
- Low Leakage Current
- Two "BAV70" Circuits in One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (BAV70HDWQ)

### **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208@3
- Orientation: See Diagram
- Weight: 0.006 grams (Approximate)

**SOT363** 



Top View



Top View Internal Schematic

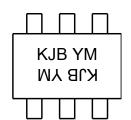
### Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BAV70HDW-7	AEC-Q101	SOT363	3.000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



KJB = Product Type Marking Code YM = Date Code Marking Y = Year ex: C = 2015 M = Month ex: 9 = September

Date Code Key

Year	2015		2016	2017		2018	2019		2020	2021		2022
Code	С		D	Е		F	G		Н	I		J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>R</sub> WM V <sub>R</sub>	100	V
RMS Reverse Voltage		$V_{R(RMS)}$	71	V
Forward Continuous Current (Note 5)		I <sub>FM</sub>	250	mA
Average Rectified Output Current (Note 5)		lo	125	mA
Repetitive Peak Forward Current		I <sub>FRM</sub>	450	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I <sub>FSM</sub>	4 1 0.5	A

### **Thermal Characteristics**

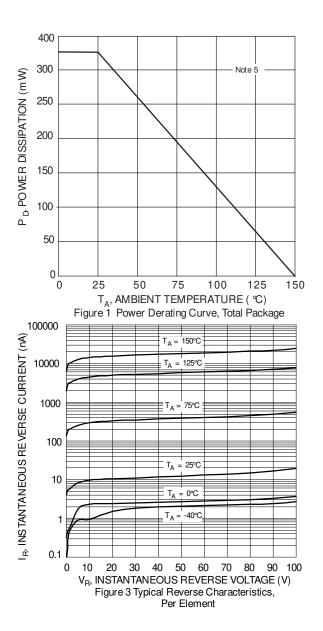
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	350	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	R <sub>0JA</sub>	357	°C/W
Thermal Resistance, Junction to Solder Point	$R_{ heta JSP}$	255	°C/W
Operating and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-65 to +150	°C

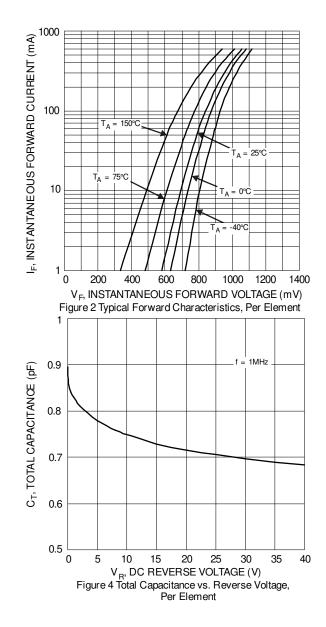
### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)		100	_	V	$I_R = 20\mu A$
Forward Voltage	V <sub>F</sub>		0.715 0.855 1.0 1.25	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Reverse Current (Note 6)	I <sub>R</sub>		0.5 100 30 30	μΑ μΑ μΑ nA	$V_R = 80V$ $V_R = 80V, T_J = +150^{\circ}C$ $V_R = 25V, T_J = +150^{\circ}C$ $V_R = 25V$
Total Capacitance	Ст		1.5	pF	$V_R = 0$ , $f = 1.0MHz$
Reverse Recovery Time	t <sub>RR</sub>	_	4.0	ns	$\begin{split} I_F &= I_R = 10 \text{mA}, \\ I_{RR} &= 0.1 \text{ x } I_R, \text{ R}_L = 100 \Omega \end{split}$
Forward Recovery Voltage			1.75	V	$I_F = 10mA, t_R = 20ns$

5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html. 6. Short duration pulse test used to minimize self-heating effect. Notes:





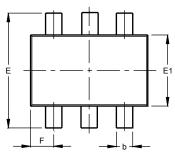


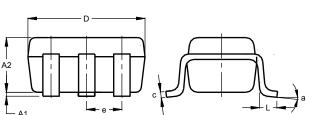


## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT363**



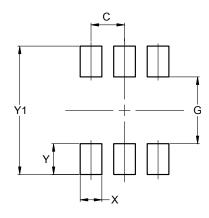


	SOT363						
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	1.00				
b	0.10	0.30	0.25				
С	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	(	).650 E	SC				
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°	_				
All	All Dimensions in mm						

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT363**



Dimensions	Value (in mm)		
С	0.650		
G	1.300		
X	0.420		
Υ	0.600		
V1	2 500		



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